L	Hits	Search Text	DB	Time stamp
Number		,		
1	132746	connector and cable	USPAT;	2003/09/28
			US-PGPUB;	21:59
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
2	2331891	(integrated adj circuit) ic semiconductor	USPAT;	2003/09/28
		die chip	US-PGPUB;	22:00
			EPO; JPO;	İ
			DERWENT;	
			IBM_TDB	·
3	28451	(connector and cable) and ((integrated	USPAT;	2003/09/28
		adj circuit) ic semiconductor die chip)	US-PGPUB;	22:01
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
4	6872	(substrate carrier) and (pcb board cb pb	USPAT;	2003/09/28
		((printed circuit) adj3 board)) and	US-PGPUB;	22:02
		((connector and cable) and ((integrated	EPO; JPO;	,
		adj circuit) ic semiconductor die chip))	DERWENT;	
			IBM_TDB	
5	3280	((substrate carrier) and (pcb board cb pb	USPAT;	2003/09/28
		((printed circuit) adj3 board)) and	US-PGPUB;	22:03
		((connector and cable) and ((integrated	EPO; JPO;	
		adj circuit) ic semiconductor die chip)))	DERWENT;	
		and (package packaging packaged)	IBM_TDB	
6	1979	(((substrate carrier) and (pcb board cb	USPAT;	2003/09/28
		pb ((printed circuit) adj3 board)) and	US-PGPUB;	22:03
		((connector and cable) and ((integrated	EPO; JPO;	
		adj circuit) ic semiconductor die chip)))	DERWENT;	
		and (package packaging packaged)) and	IBM_TDB	[
		(trace wiring)		

L Number	Hits	Search Text	DB	Time stamp
1	132746	connector and cable	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/09/28 21:59
2	2331891	(integrated adj circuit) ic semiconductor die chip	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/09/28 22:00
3	28451	(connector and cable) and ((integrated adj circuit) ic semiconductor die chip)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/09/28 22:01
	6872	<pre>(substrate carrier) and (pcb board cb pb ((printed circuit) adj3 board)) and ((connector and cable) and ((integrated adj circuit) ic semiconductor die chip))</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/09/28 22:02
5	3280	<pre>((substrate carrier) and (pcb board cb pb ((printed circuit) adj3 board)) and ((connector and cable) and ((integrated adj circuit) ic semiconductor die chip))) and (package packaging packaged)</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/09/28 22:03
6	1979	(((substrate carrier) and (pcb board cb pb ((printed circuit) adj3 board)) and ((connector and cable) and ((integrated adj circuit) ic semiconductor die chip))) and (package packaging packaged)) and (trace wiring)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/28 22:03
7	1867	((((substrate carrier) and (pcb board cb pb ((printed circuit) adj3 board)) and ((connector and cable) and ((integrated adj circuit) ic semiconductor die chip))) and (package packaging packaged)) and (trace wiring)) and (signaling signal)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/28 22:04
8	1610	(((((substrate carrier) and (pcb board cb pb ((printed circuit) adj3 board)) and ((connector and cable) and ((integrated adj circuit) ic semiconductor die chip))) and (package packaging packaged)) and (trace wiring)) and (signaling signal)) and method and system	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/28 22:04